CLAIMS

1. A silver-bismuth powder, comprising metals and an oxygen content,

wherein the metals consist of silver and bismuth,

wherein a mass ratio, silver:bismuth, of the silver to the bismuth is 95:5 to 40:60,

wherein a cumulative 50% point of particle diameter (D50) of the silver-bismuth powder in a volume-based particle size distribution thereof as measured by a laser diffraction particle size distribution analysis is 0.1 μm to 10 μm, and

wherein the oxygen content of the silver-bismuth powder is 5.5% by mass or less.

2. The silver-bismuth powder according to claim 1, wherein the silver is 50% to 95% of the metals by mass.

3. The silver-bismuth powder according to claim 1 or claim 2, wherein the cumulative 50% point of particle diameter (D50) of the silver-bismuth powder in the volume-based particle size distribution thereof as measured by the laser diffraction particle size distribution analysis is 0.5 μm to 4 μm.

4. The silver-bismuth powder according to any one of claims 1 to 3, wherein the silver is 70% to 95% of the metals by mass.

5. The silver-bismuth powder according to any one of claims 1 to 4, wherein the silver-bismuth powder is produced by a water atomization process.

6. A conductive paste, comprising:

the silver-bismuth powder according to any one of claims 1 to 5;

a resin;

a glass frit; and

a solvent.

7. The conductive paste according to claim 6, wherein a softening point of the glass frit is 400°C to 600°C.

8. A conductive film, obtained by a method including:

burning the conductive paste according to claim 6 or 7.

9. The conductive film according to claim 8, wherein the burning is performed at a temperature equal to or higher than a softening point of the glass frit.